



## Material Content Data Sheet



<b>Sales Product Name</b>	BGSA 402ML10 E6327			<b>Issued</b>	4. July 2019			
<b>MA#</b>	MA005072842							
<b>Package</b>	PG-TSLP-10-2			<b>Weight*</b>	1.45 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.543	37.34	37.34	373397	373397
bumps	non noble metal	copper	7440-50-8	0.012	0.86	0.86	8585	8585
leadframe	non noble metal	nickel	7440-02-0	0.104	7.16	7.16	71598	71598
encapsulation	organic material	carbon black	1333-86-4	0.004	0.26		2580	
	plastics	epoxy resin	-	0.109	7.48		74834	
	inorganic material	silicondioxide	60676-86-0	0.638	43.86	51.60	438683	516097
leadfinish	noble metal	gold	7440-57-5	0.015	1.03	1.03	10334	10334
plating	noble metal	silver	7440-22-4	0.025	1.69	1.69	16875	16875
solder	noble metal	silver	7440-22-4	0.000	0.01		56	
	non noble metal	tin	7440-31-5	0.004	0.31	0.32	3058	3114
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com